

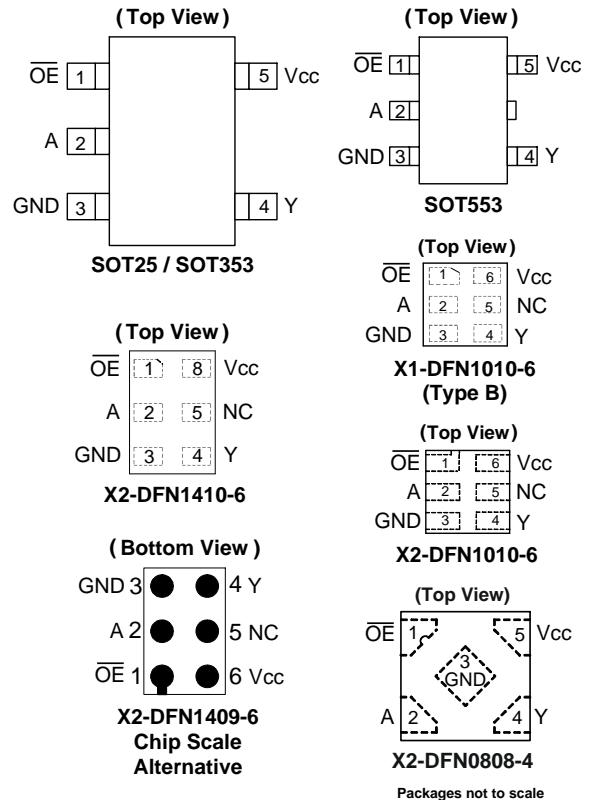
## Description

The 74LVC1G125 is a single, non-inverting buffer/bus driver with a 3-state output. The output enters a high-impedance state when a HIGH-level is applied to the output enable ( $\overline{OE}$ ) pin. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V, allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

## Features

- Wide Supply Voltage Range from 1.65 to 5.5V
- $\pm 24\text{mA}$  Output Drive at 3.3V
- CMOS Low Power Consumption
- $I_{OFF}$  Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Direct Interface with TTL Levels
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Pin Assignments

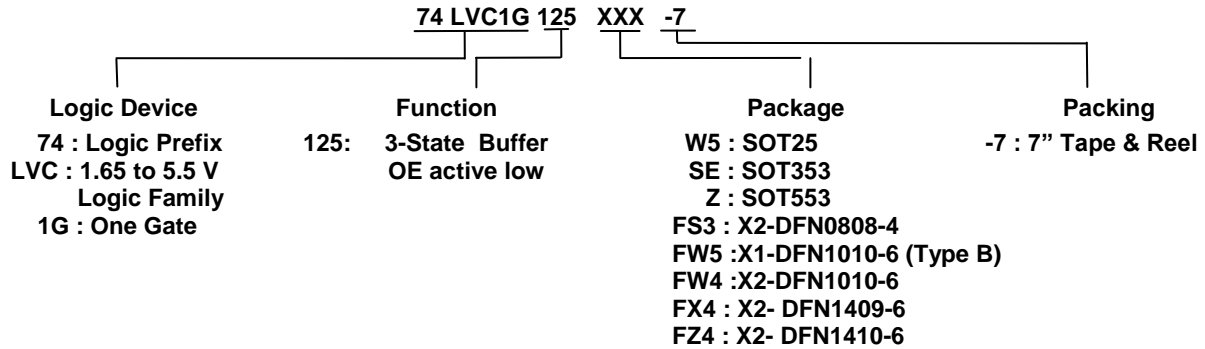


## Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-readers
  - Computer Peripherals, Hard Drives, CD/DVD ROMs
  - TVs, DVDs, DVRs, Set Top Boxes
  - Cell Phones, Personal Navigation / GPS
  - MP3 Players, Cameras, Video Recorders

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

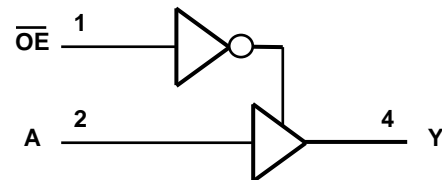
**Ordering Information** (Note 4)


Part Number	Package Code	Package (Notes 5 & 6)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G125W5-7	W5	SOT25	3.0mm x 2.8mm x 1.2mm 0.95mm lead pitch	3,000/Tape & Reel	-7
74LVC1G125SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65mm lead pitch	3,000/Tape & Reel	-7
74LVC1G125Z-7	Z	SOT553	1.6mm x 1.6 mm x 0.62mm 0.5mm lead pitch	4,000/Tape & Reel	-7
74LVC1G125FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8 mm x 0.35mm 0.5mm pad pitch (diamond)	5,000/Tape & Reel	-7
74LVC1G125FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FX4-7	FX4	X2-DFN1409-6 (Chip scale alternative)	1.4mm x 0.9mm x 0.4mm 0.5mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5mm pad pitch	5,000/Tape & Reel	-7

- Notes:
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.
  5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at <http://www.diodes.com/package-outlines.html>.
  6. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Pin Descriptions**

Pin Name	Description
$\overline{OE}$	Output Enable
A	Data Input
GND	Ground
Y	Data Output
V <sub>CC</sub>	Supply Voltage
NC	No Connection

**Logic Diagram**

**Function Table**

Inputs		Output
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

**Absolute Maximum Ratings** (Notes 7 & 8) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
V <sub>I</sub>	Input Voltage Range	-0.5 to 6.5	V
V <sub>O</sub>	Voltage Applied to Output in High Impedance or I <sub>OFF</sub> State	-0.5 to 6.5	V
V <sub>O</sub>	Voltage Applied to Output in High or Low State.	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
I <sub>O</sub>	Continuous Output Current	±50	mA
I <sub>CC</sub> , I <sub>GN</sub>	Continuous Current Through V <sub>CC</sub> or GND	±100	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
  - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

**Recommended Operating Conditions** (Note 9) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V <sub>IH</sub>	High-Level Input Voltage	V <sub>CC</sub> = 1.65V to 1.95V	0.65 x V <sub>CC</sub>	—	V
		V <sub>CC</sub> = 2.3V to 2.7V	1.7	—	
		V <sub>CC</sub> = 3V to 3.6V	2	—	
		V <sub>CC</sub> = 4.5V to 5.5V	0.7 x V <sub>CC</sub>	—	
V <sub>IL</sub>	Low-Level Input voltage	V <sub>CC</sub> = 1.65V to 1.95V	—	0.35 x V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3V to 2.7V	—	0.7	
		V <sub>CC</sub> = 3V to 3.6V	—	0.8	
		V <sub>CC</sub> = 4.5V to 5.5V	—	0.3 x V <sub>CC</sub>	
V <sub>I</sub>	Input Voltage	0	5.5	V	
V <sub>O</sub>	Output Voltage	0	V <sub>CC</sub>	V	
I <sub>OH</sub>	High-Level Output Current	V <sub>CC</sub> = 1.65V	—	-4	mA
		V <sub>CC</sub> = 2.3V	—	-8	
		V <sub>CC</sub> = 2.7V	—	-12	
		V <sub>CC</sub> = 3V	—	-16	
		V <sub>CC</sub> = 4.5V	—	-32	
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 1.65V	—	4	mA
		V <sub>CC</sub> = 2.3V	—	8	
		V <sub>CC</sub> = 2.7V	—	12	
		V <sub>CC</sub> = 3V	—	16	
		V <sub>CC</sub> = 4.5V	—	32	
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 1.8V ± 0.15V, 2.5V ± 0.2V	—	20	ns/V
		V <sub>CC</sub> = 3.3V ± 0.3V	—	10	
		V <sub>CC</sub> = 5V ± 0.5V	—	5	
T <sub>A</sub>	Operating Free-Air Temperature	—	-40	+125	°C

- Note: 9. Unused inputs should be held at V<sub>CC</sub> or Ground.

**Electrical Characteristics** (All typical values are at  $V_{CC} = 3.3V$ ,  $T_A = +25^\circ C$ )

Symbol	Parameter	Test Conditions	$V_{CC}$	-40°C to +85°C			-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
$V_{OH}$	High-Level Output Voltage	$I_{OH} = -100\mu A$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	$V_{CC} - 0.1$	—	V
		$I_{OH} = -4mA$	1.65V	1.2	—	—	0.95	—	
		$I_{OH} = -8mA$	2.3V	1.9	—	—	1.7	—	
		$I_{OH} = -12mA$	2.7V	2.2	—	—	1.9	—	
		$I_{OH} = -16mA$	3V	2.4	—	—	2.2	—	
		$I_{OH} = -24mA$		2.3	—	—	2.0	—	
		$I_{OH} = -32mA$	4.5V	3.8	—	—	3.4	—	
$V_{OL}$	Low-Level Output Voltage	$I_{OL} = 100\mu A$	1.65V to 5.5V	—	—	0.1	—	0.1	V
		$I_{OL} = 4mA$	1.65V	—	—	0.45	—	0.7	
		$I_{OL} = 8mA$	2.3V	—	—	0.3	—	0.45	
		$I_{OL} = 12mA$	2.7V	—	—	0.4	—	0.6	
		$I_{OL} = 16mA$	3V	—	—	0.4	—	0.6	
		$I_{OL} = 24mA$		—	—	0.55	—	0.8	
		$I_{OL} = 32mA$	4.5V	—	—	0.55	—	.8	
$I_I$	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V	—	$\pm 0.1$	$\pm 5$	—	$\pm 100$	$\mu A$
$I_{OFF}$	Power Down Leakage Current	$V_I$ or $V_O = 5.5V$	0V	—	—	$\pm 10$	—	$\pm 200$	$\mu A$
$I_{OZ}$	Z State Leakage Current	$V_O = 0$ to 5.5V	3.6V	—	0.1	10	—	20	$\mu A$
$I_{CC}$	Supply Current	$V_I = 5.5V$ or GND $I_O = 0$	5.5V	—	0.1	10	—	200	$\mu A$
$\Delta I_{CC}$	Additional Supply Current	Input at $V_{CC} - 0.6V$	3V to 5.5V	—	—	500	—	5,000	$\mu A$
$C_i$	Input Capacitance	$V_i = V_{CC} -$ or GND	3.3V	—	5	—	—	—	pF

**Package Characteristics** (All typical values are at  $V_{CC} = 3.3V$ ,  $T_A = +25^\circ C$ )

Symbol	Parameter	Test Conditions	$V_{CC}$	Min	Typ	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT25	(Note 10)	—	204	—	$^\circ C/W$
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6 (Type B)		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
$\theta_{JC}$	Thermal Resistance Junction-to-Case	SOT25	(Note 10)	—	52	—	$^\circ C/W$
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6 (Type B)		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 10. Test condition for each of the eight package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

## Switching Characteristics

Figure 1 Typical Values at  $T_A = +25^\circ\text{C}$  and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

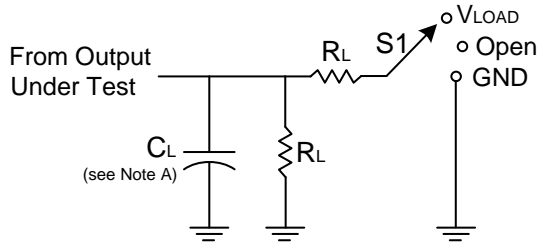
Parameter	From Input	To Output	$V_{CC}$	$T_A = -40^\circ\text{C to } +85^\circ\text{C}$			$T_A = -40^\circ\text{C to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	
$t_{pd}$	A	Y	$1.8V \pm 0.15V$	1.0	3.3	8.0	1.0	10.5	ns
			$2.5V \pm 0.2V$	0.5	2.2	5.5	0.5	7.0	
			2.7V	0.5	2.5	5.5	0.5	7.5	
			$3.3V \pm 0.3V$	0.5	2.1	4.5	0.5	6.0	
			$5.0V \pm 0.5V$	0.5	1.7	4.0	0.5	5.5	
$t_{en}$	$\overline{OE}$	Y	$1.8V \pm 0.15V$	1.0	4.1	9.4	1.0	12.0	ns
			$2.5V \pm 0.2V$	0.5	2.8	6.6	0.5	8.5	
			2.7V	0.5	3.3	6.6	0.5	8.5	
			$3.3V \pm 0.3V$	0.5	2.4	5.3	0.5	7.0	
			$5.0V \pm 0.5V$	0.5	2.1	5.0	0.5	6.5	
$t_{dis}$	$\overline{OE}$	Y	$1.8V \pm 0.15V$	1.0	4.3	9.2	1.0	12.0	ns
			$2.5V \pm 0.2V$	0.5	2.7	5.0	0.5	6.5	
			2.7V	0.5	3.0	5.0	0.5	6.5	
			$3.3V \pm 0.3V$	0.5	3.1	5.0	0.5	6.5	
			$5.0V \pm 0.5V$	0.5	2.2	4.2	0.5	5.5	

## Operating Characteristics

$T_A = +25^\circ\text{C}$

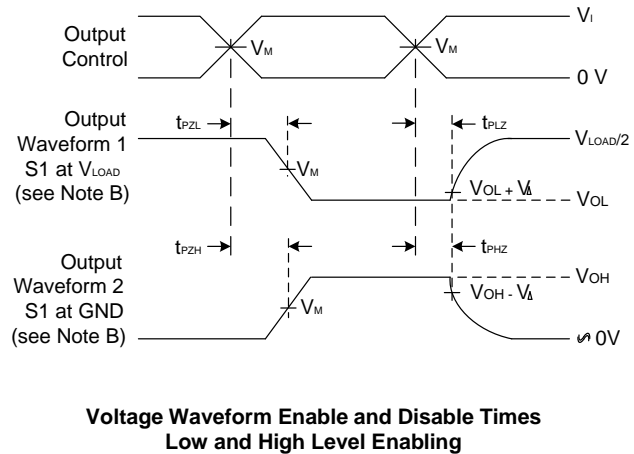
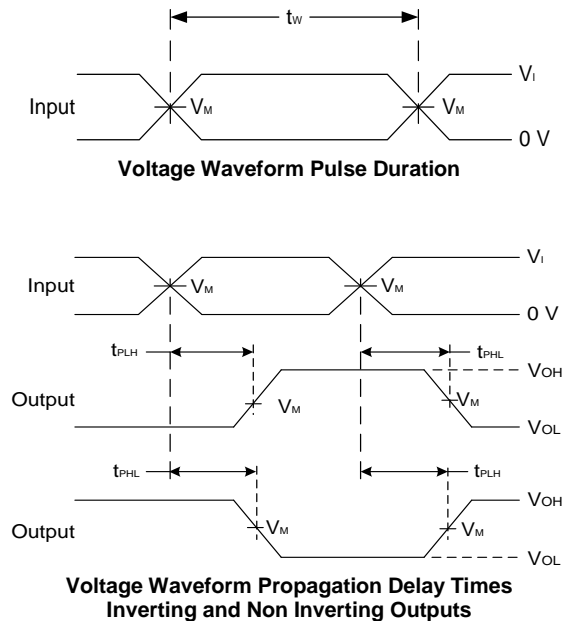
Parameter			Test Conditions	$V_{CC} = 1.8V$	$V_{CC} = 2.5V$	$V_{CC} = 3.3V$	$V_{CC} = 5V$	Unit
				Typ	Typ	Typ	Typ	
$C_{pd}$	Power Dissipation Capacitance	Outputs Enabled	$f = 10\text{MHz}$	19	19	19	21	pF
		Outputs Disabled		2	2	3	4	

**Parameter Measurement Information**



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	Inputs		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8V \pm 0.15V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1k $\Omega$	0.15V
$2.5V \pm 0.2V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 $\Omega$	0.15V
2.7V	2.7V	$\leq 2.5ns$	1.5V	6V	50pF	500 $\Omega$	0.3V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500 $\Omega$	0.3V
$5V \pm 0.5V$	$V_{CC}$	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500 $\Omega$	0.3V

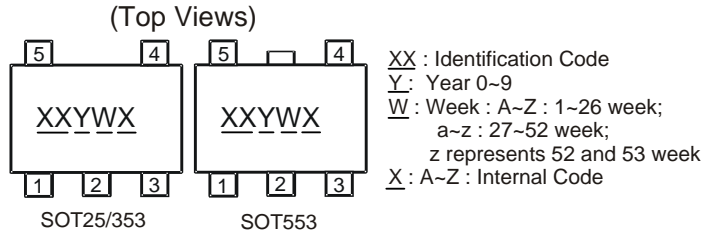


**Figure 1 Load Circuit and Voltage Waveforms**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq 10MHz$ .
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN}$ .
  - F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

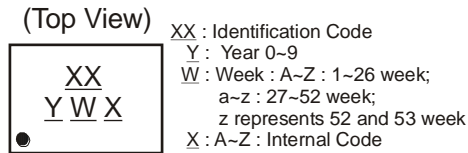
## Marking Information

### (1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G125W5-7	SOT25	UY
74LVC1G125SE-7	SOT353	UY
74LVC1G125Z-7	SOT553	UY

### (2) DFN Packages

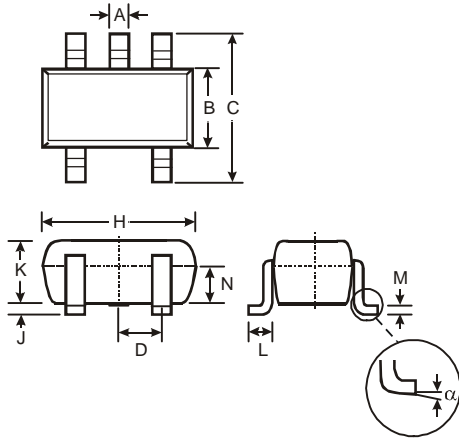


Part Number	Package	Identification Code
74LVC1G125FS3-7	X2-DFN0808-4	WY
74LVC1G125FW5-7	X1-DFN1010-6 (Type B)	VY
74LVC1G125FW4-7	X2-DFN1010-6	UY
74LVC1G125FX4-7	X2-DFN1409-6	MW
74LVC1G125FZ4-7	X2-DFN1410-6	UY

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT25**

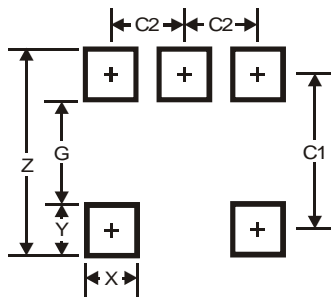


SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT25**



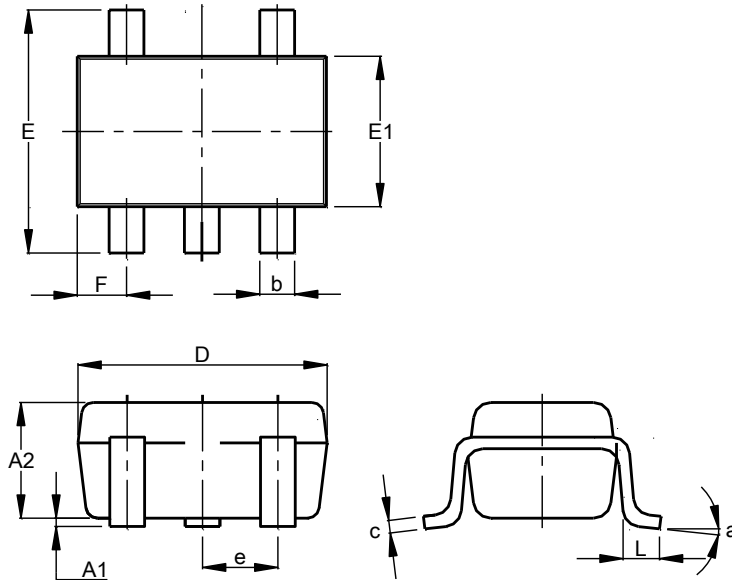
Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT353**

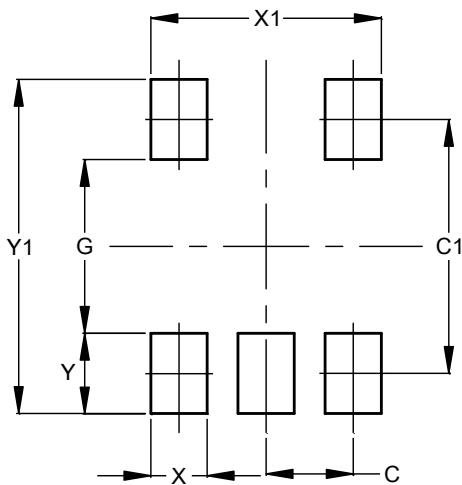


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT353**

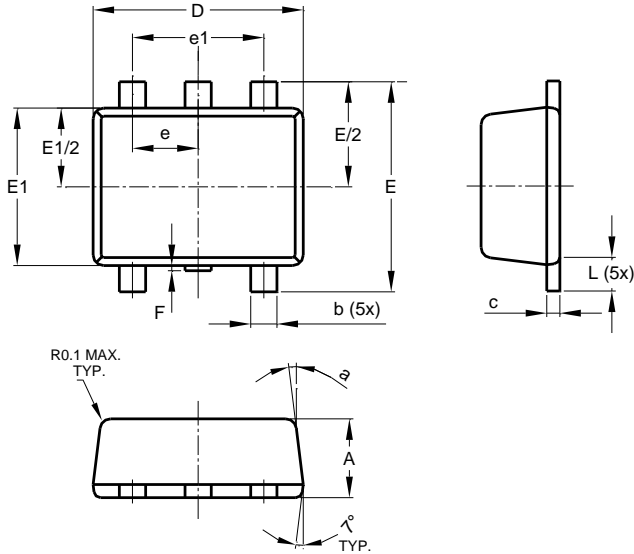


Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT553**

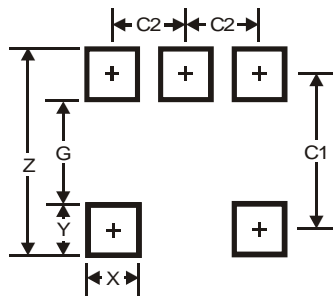


SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT553**



Dimensions	Value
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4



X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4

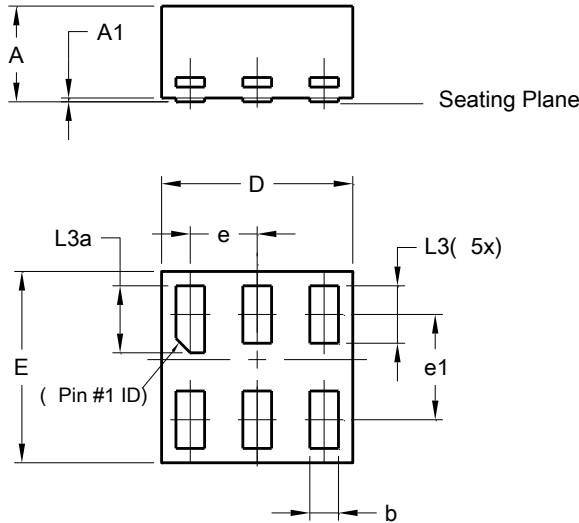


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1010-6 (Type B)**

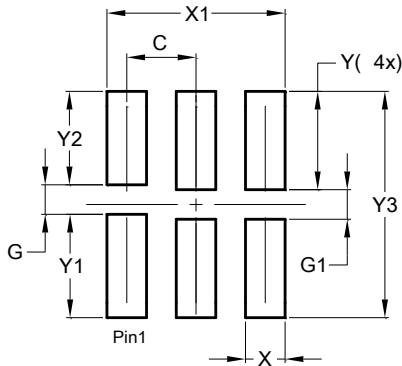


X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1010-6 (Type B)**

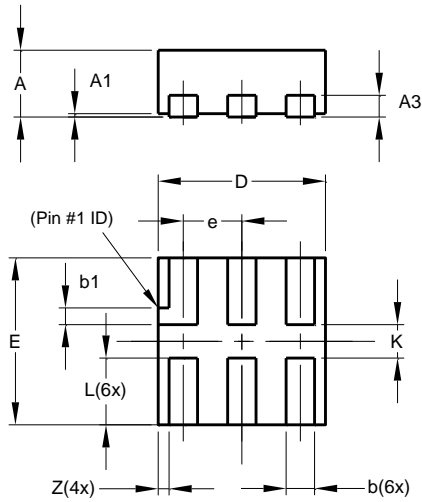


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1010-6**

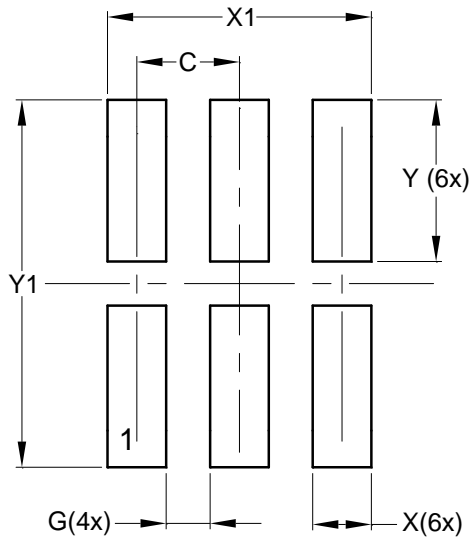


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1010-6**

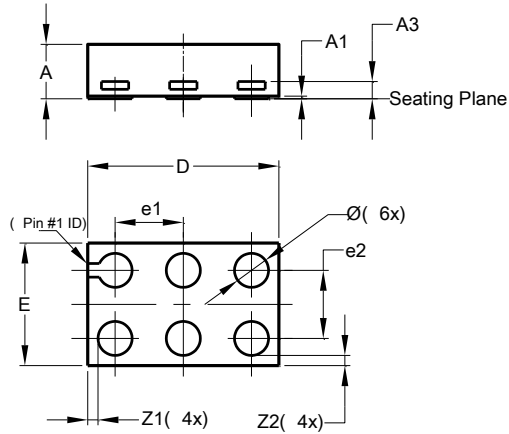


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1409-6 CHIP SCALE ALTERNATIVE**

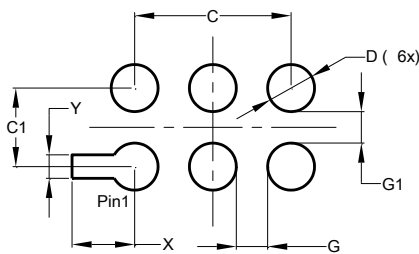


X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1409-6 CHIP SCALE ALTERNATIVE**

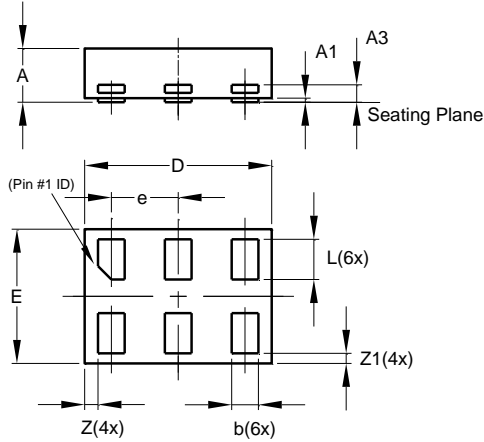


Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1410-6**

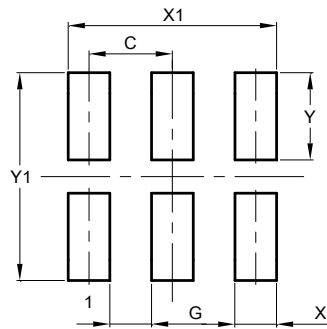


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DFN1410-6**



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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